

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L2	3419	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L3	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L4	0	L3 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L5	434	L2 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L6	323	L2 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L7	88	L6 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L8	180	("4604644" / "4825284" / "4970575" / "4987100" / "5107325" / "5177669" / "5222014" / "5239198" / "5249101" / "5291062" / "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L9	43	L2 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L10	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L11	2596	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L12	699	L11 and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L13	12	("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L14	3	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/02/03 21:00
L15	143	lead with substrate with bump and 257/778.ccls.	USPAT	OR	ON	2008/02/03 21:00
L16	6	("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L17	24	("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L18	20	("4706811" "4758407" "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L19	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00

L20	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L21	14	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L22	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L23	8	("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L24	7	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L25	7	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L26	12818	lead with bump ssame solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L27	5383	lead with bump ssame solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L28	21	lead with bump same solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L29	5	("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L30	43	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L31	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L32	44	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/02/03 21:00
L33	17	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/02/03 21:00
L34	38	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2008/02/03 21:00
L35	88	L32 L33 L34	USPAT	OR	ON	2008/02/03 21:00
L36	88	L32 L33 L34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L37	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L38	3419	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L39	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L40	0	L39 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L41	434	L38 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L42	323	L38 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L43	88	L42 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L44	180	("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L45	43	L38 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L46	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L47	2596	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L48	699	L47 and "257"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L49	12	("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L50	3	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/02/03 21:00
L51	143	lead with substrate with bump and 257/778.ccls.	USPAT	OR	ON	2008/02/03 21:00
L52	6	("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L53	24	("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L54	20	("4706811" "4758407" "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L55	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L56	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L57	3683	(257/e23.021).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L58	2	L57 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L59	0	L57 and solder near2 (resist mask) with underfill with wetab \$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L60	0	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab \$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L61	142	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L62	136	(257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L63	52	(257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L64	18	("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L65	73038	(257/e23.\$4).ccls. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L66	0	(257/e23.\$4).ccls. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L67	0	(257/e23.\$4).ccls. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L68	0	(257/e23.\$4).ccls. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L69	19	(257/e23.\$4).ccls. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L70	1	(257/e23.\$4).ccls. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L71	1	("257"/\$6).ccls. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L72	0	("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L73	0	("257"/\$6).ccls. and solder near2 (resist mask) with underfill \$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L74	2	("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L75	28	("257"/\$6).ccls. and solder near2 (resist mask) with (improv \$3, increas\$3) with attach\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L76	4	("5703402" "5801440" "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L77	20	("4706811" "4758407" "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L78	24	("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L79	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L80	12	("4604644" / "5084961" / "5089440" / "5121190" / "5194930" / "5274913" / "5400950" / "5542601" / "5578525" / "5615477" / "5704116" / "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L81	125	("5710071").URPN.	USPAT	OR	ON	2008/02/03 21:00
L82	6	"5, 71, 071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L83	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L84	2	"5, 710, 071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L85	11	("4604644" / "5144747" / "5182632" / "5203076" / "5218234" / "5296738" / "5311059" / "5385869" / "5473512" / "5488200" / "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L86	111	("4138691" / "4268848" / "4280132" / "4843036" / "5001542" / "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L87	3290	257/778.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L88	637	L87 and solder near2 (resist mask)	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L89	350	L88 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L90	245	L88 and polyimide	USPAT	OR	ON	2008/02/03 21:00
L91	29	("4658332" "4740414" "4847136" "4847146" "4855872" "4873615" "5026624" "5110867" "5258648" "5262280" "5278010" "5304457" "5329423" "5391435" "5439766" "5439779" "5473119" "5493075" "5496769" "5511306" "5535101" "5579573" "5633535" "5801446" "5808874" "5821305" "5866952" "6002590" "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L92	150	("4604644" "4864470" "4931345" "5107325" "5172303" "5241133" "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L93	1809657	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polymide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L94	105857	L93 and "438"/\$. ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L95	64423	L93 and "438"/\$. ccls.	USPAT	OR	ON	2008/02/03 21:00
L96	35003	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polymide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L97	2267	L96 and "438"/\$. ccls.	USPAT	OR	ON	2008/02/03 21:00
L98	21320	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L99	347027	L98 and solder ball	USPAT	OR	ON	2008/02/03 21:00
L100	300	L98 and solder near2 ball	USPAT	OR	ON	2008/02/03 21:00
L101	13	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L102	39	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L103	26	L102 not L101	USPAT	OR	ON	2008/02/03 21:00
L104	7	("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L105	39	("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L106	1009	thin with polyimide with substrate and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L107	639	thin with polyimide with substrate and "257"/\$.ccls.	USPAT	OR	ON	2008/02/03 21:00
L108	52	thin with polyimide with substrate with "mu.m" and "257"/\$. ccls.	USPAT	OR	ON	2008/02/03 21:00
L109	229	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L110	132	L109 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L111	179	L109 not L108	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L112	79	L109 not L108	USPAT; USOCR	OR	ON	2008/02/03 21:00
L113	393	(IC integrated nearl circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L114	232	(IC integrated nearl circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/02/03 21:00
L115	0	jp-361633-\$.did.	USPAT	OR	ON	2008/02/03 21:00
L116	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L117	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L118	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L119	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L120	20	("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. OR ("6518649").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L121	18	("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L122	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L123	17	("4551912" "4811081" "4851964" "4977441" "5032542" "5075252" "5153707" "5232532" "5427641" "5726491" "5949134" "6100112" "6274405" "6313526" "6315156" "6388888" "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L124	7	("5260168" / "5378581" / "5825081" / "6313526" / "6320135" / "6388888" / "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L125	18	("20010002066" / "20010040290" / "20010054751" / "4263606" / "4676864" / "4786545" / "4963974" / "5049718" / "5060052" / "5132772" / "5139610" / "5384204" / "5844304" / "5910685" / "6028011" / "6175151" / "6262488" / "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L126	2	jip-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L127	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L128	1028	(257/797).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L129	7	L128 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L130	14	L128 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

2/3/08 9:50:10 PM

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